

IN THE SPECIFICATION:

Please substitute the following paragraph for the paragraph starting at page 17, line 23 and ending at page 18, line 9.

As the seal bonding material to be arranged in the corner portion 12, it is preferable to use a low-melting substance. In this embodiment mode, indium (In) as a low-melting metal is adopted. In is a material with a relatively low melting point of 156°C and little gas emission at the melting point (softening point). Although heating of up to approximately 500°C is required when using a fit frit glass, heating of up to 200°C suffices when using In, making it possible to attain an effect of simplifying the manufacturing process. Indium alloy is also known as such low-melting substance in addition to pure indium, and thus indium alloy may also be suitably used.

Please substitute the following paragraph for the paragraph starting at page 28, line 16 and ending at page 29, line 6.

According to conventional manufacturing methods, airtightness is secured by the fit frit glass as a seal bonding material filling in the irregularities of the surface of the glass substrate. Thus, it is necessary to apply a predetermined pressure in a uniform manner. Accordingly, it is necessary to provide a high-accuracy mechanism for applying a uniform pressure and to perform a feedback control on positional displacement accompanying the substrate deformation due to an applied pressure, and thus those conventional methods require a large manufacturing apparatus, leading to an increase in manufacturing cost. However, according to the present invention, there

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is no need to apply a large pressure, nor it is necessary to give particular consideration to the uniformity of the applied pressure, thus attaining effects such as improved yield, etc.